

**SUPPORTING STRUCTURE FOR A CHIP AND METHOD FOR PRODUCING
THE SAME**

ABSTRACT

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A supporting structure for a chip includes a supporting
substrate with a bond opening therein and an interconnect
layer on the supporting substrate. In the interconnect
layer, a bonding channel overlapping with the bond opening
10 is formed. The supporting structure further includes an
escape prevention structure for the bonding channel to
enable escaping of air from the bonding channel and to
prevent the encapsulation material from escaping from the
bonding channel on introducing encapsulation material into
15 the bonding channel after the applying of a chip to the
supporting structure.